Special Issue

Integration of MEMS, 3D Printing, and Nano-Enabled Technologies in Wireless Communication and Sensing Systems

Message from the Guest Editors

This Special Issue highlights the latest research and developments in reconfigurable wireless communication and sensing systems, with a focus on interdisciplinary approaches that combine MEMS, 3D printing, and nanotechnology. Topics include but are not limited to the following:

- Design and fabrication of reconfigurable antennas and sensors using MEMS and 3D printing;
- Nano-enabled materials for enhanced signal processing, energy harvesting, and sensing capabilities;
- Applications in IoT, 5G/6G networks, healthcare, environmental monitoring, and smart infrastructure;
- Challenges and opportunities in the scaling, integration, and commercialization of these technologies.

By bringing together contributions from leading researchers and industry experts, this Special Issue will provide a comprehensive overview of the state of the art and inspire future innovations in reconfigurable wireless communication and sensing systems. We invite original research articles, reviews, and case studies that demonstrate the transformative impact of MEMS, 3D printing, and nano-enabled technologies in this dynamic field.

Guest Editors

Dr. Ignacio Llamas-Garro

Centre Tecnològic de Telecomunicacions de Catalunya, CTTC/CERCA, 08860 Castelldefels, Spain

Dr. Satyendra Kumar Mishra

Centre Tecnològic de Telecomunicacions de Catalunya, CTTC/CERCA, 08860 Castelldefels, Spain

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Micromachines
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
micromachines@mdpi.com

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Editor-in-Chief

Prof. Dr. Ai-Qun Liu
1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

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